- Manufacturer: TEL ACT12-300 Dual Block Track
- Tool Type: Dual Process Block Track
- Model: ACT12-300
- Wafer Size: 300mm
- Direction: RIGHT HAND SIDE
- 4 Blocks Interfaced; Cassette, 2 Process, & Stepper Interface
- 4 Wafer Transfer Robot Arms; Cassette, 2 Process, & Stepper Interface
- Control Module on cassette end station (CES)
- 3 Station 25 wafer FOUP
- Interface is to Ultratech T-300
- Cassette rotators and platforms
- Facility sensors for DI water and Caustic exhaust
- Coater (COT) - quantity 1
- Coater (PCT) - quantity 2
    - 2 Nozzles w/ Temperature Control
    - Chuck vacuum sensor
    - Millipore P-250 pumps
    - SS 0.3mm diameter side rinse nozzle w/ flow meter
    - 1 set of 2 SS 0.3mm diameter back rinse nozzles
    - 1 SS 0.3mm diameter back rinse nozzle for chemical 1
    - 1 SS 0.3mm diameter back rinse nozzle for chemical 2
    - Bulk-FSI system for side and back rinse
    - PTI mass flow controller per module
    - PP cup w/ sensor
    - Chuck Up VAC Off Switch
    - Addition of drip trays
- Developer (DEV) - quantity 4
    - 1 “H” nozzle w/ temperature control per cup
    - Bulk-FSI system for developer
    - PP cup w/ sensor
    - Chuck vacuum sensor
    - Chuck Up VAC Off Switch
- Chill Plate Process Station (CPL) - quantity 6
    - Hard anodized aluminum oxalic acid treated surface plate AL
    - Temperature Control
    - 0.1 mm C ring fixed type and spacer type stainless & polyimide proximity pins
    - Dual-Band alarm function
- Transfer Chill Plate (TCP) – quantity 1
    - Hard anodized aluminum oxalic acid treated surface plate Al
    - 0.1mm C ring fixed type and spacer type stainless & polyimide proximity pins
- Adhesion Process Station (ADH) – quantity 1

- Half-sealed chamber w/ dispersion plate for HMDS
- Dual-band alarm function
- 10L canister w/ Bubble sensor

- Heated Cover High Exhaust Low Temp Hot Plate Process Station (HCH) - quantity 8
  - N2 purge capability
  - High volume exhaust
  - Mist traps
  - SS insulated heated exhaust cover w/ cover interlock
  - Hard anodized aluminum oxalic acid treated Al surface plate
  - Temperature control
  - 0.1mm C ring fixed type and spacer type stainless & polyimide proximity pins
  - Dual-band alarm function
  - Individual thermo-switch for overheating detection
- Interface Block - quantity 1
  - Single-pincette shared wafer transfer w/ centering guides; standard wafer arm and interface panel to accommodate Ultratech T-300 (May vary)
  - Interface must include a CPL for insuring consistent wafer temps into the stepper; (IFCPL)
  - Buffer cassette; 26 wafer capability
  - Wafer out sensor
  - WEE requires 435nm spectrum for G-line application
- TEL Temperature and Humidity Controller - 2
- Fluid Temperature Controller – 1
- Chemical Cabinet – 1
  - DI H20 facility sensors
  - 4- 1gal C4 bottles w/ recirculation feature
  - 2- 20L reserve Tank s w/ 2- 3L buffer tanks for solvent
  - 2- 20L reserve Tank s w/ 2- 3L buffer tanks for develop
  - 300cc L/E for solvent
  - 8- 200cc L/E for C4
  - 1- Solvent panel
  - 1- Develop panels
  - 2- auto change air valves
- AC Power Box – 1

Connection:	CONNECTED
Tracing:	IDLE
Process State:	IDLE
HOST Control:	ON-LINE/LOCAL
ARAMS State:	
Tool Time:	2023/08/22 15:04

Cassette State

#	State	Supply	Proc	End	Carrier ID
	IDLE	0	0	0	
	IDLE	0	0	0	
	IDLE	0	0	0	

Job/Alarm State

